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(30) Priority:	(71) Applicant: SUGANUMA KEIICHIRO
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**(54) METHOD FOR
PRODUCING
SEMICONDUCTOR AND
DEVICE THEREFOR**

(57) Abstract:

PURPOSE: To subject a semiconductor wafer to plating in a uniform thickness and to carry out chemical treatment or other treatment.

CONSTITUTION: A semiconductor wafer W is held over a treating vessel 1 with the top open so that the surface of the wafer W to be treated is positioned downward, a treating soln. is fed from plural parts in the treating vessel 1 and electric current is supplied between a lower electrode 2 and an upper electrode 3 disposed in the vessel 1 while allowing the treating soln. to overflow the vessel 1 to subject the semiconductor wafer W to plating, chemical treatment or other treatment.

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